INDEX TO PLATING VOL. 53, 1966

A

About Two Microstructural Features of Electrodeposits, R. Weil and W. N. Jacobus Jr. 102
Accelerated Electrolytic Corrosion Test and a Corrosion Analysis Procedure for the Nickel-Chromium Plating System—Part I., R. L. Saur and R. P. Basco 35

ADHESION

Adhesion of Chromium Deposited on Steel, Influence of Etch Bath on the, W. H. Dancy and A. Zavarella 618
Adhesion of Plated Coatings on Selected Areas of Aluminum Alloys, Improving Adhesion of, M. Ben and W. D. Brooks 480
Adhesion to Decorative Trim, Paint, W. S. Garwood 1323

AES

AES Educational Tour to South America 1024, 1250
AES Research Project No. 23—Initial Stages of Nickel Deposition: I. The Watts Bath, M. H. Jones and M. G. Kenez .. 995
AES Educational Tour to South America 1131
AES Expands and Diversifies Its Publication Features, W. H. Safranek (Editorial) 1291
AES Research Project No. 12—Cleaning and Preparation of Metals Prior to Electroplating XVII. The Effect of Stearic Acid Films on the Overpotential for Hydrogen Evolution, M. A. Farrell and H. B. Linford 1110
AES Research Project No. 21—Physical and Mechanical Properties of Electrodeposited Copper II. The Sulfate Bath, V. A. Lamb and D. R. Valentine 86
AES-Sponsored Research, Changing Nature of, D. R. Turner (Editorial) 283
Annual Report, 1965–1966 633
Branch Directory 1366
Colorful Dallas Beckons AES for '67 804
Constitution and Bylaws 506
Dallas Convention Program Shaping Up 1470
Dallas—Shiny, New AES Convention City 1176
Educational Program, 53rd AES Annual Convention 487, 626
Fifty-Third AES Convention in Miami Beach Sponsored by Dixie Regional Council with Southeastern Branch as Host ... 1013
Financial Report 1246
Four Society Papers Win Six Awards 920
Linford, Henry B.—AES Scientific Achievement Award Recipient .. 920
Miami Beach: City of Color and Contrast, L. R. Diveley 1132
Nominees for National Office and Board of Directors 241
Plating in the Electronics Industry Symposium Program 1560
Profiles of Nominees for AES Second Vice President 490
Profiles of Nominees for Board of Directors 490
Program, AES 53rd Annual Convention 625
Quarterly Report of AES Vice Chairman for Research, M. M. Beckwith 354
Quarterly Research Report, M. M. Beckwith 1011
Reports of 1965–66 Board and Committee Chairmen and Liaison Representatives to Other Societies 800
Research Activities of the American Electroplaters' Society, W. Blum 341
Tentative Program, 53rd AES Annual Convention 486
Airless Spray Painting, J. H. Reichenbach 991
Airline Plating Forum, Second, Keynote Address, T. P. Murphy 705
Alford, E. F.
Electrodeposition of Paint 478

ALUMINUM

Aluminum Alloys, Chemical Composition of Sulfuric Acid Anodic Films on, R. C. Spooner 451
Aluminum Alloys, Electroplating on, D. W. Levinson and L. F. Mondolfo 986
Aluminum Alloys, Improving Adhesion of Plated Coatings on Selected Areas of, M. Ben and W. D. Brooks 480
Aluminum Bright Anodizing Process, Quality and Cost Improvement in the. III, The Recovery of Phosphoric Acid from Aluminum Bright Dip Rinse Solution, G. D. Nelson, C. P. Schumacher, W. J. Shortreed, and J. T. Sommerfeld 72
Aluminum Bright Anodizing Process, Quality and Cost Improvement in the. IV. Trouble-Shooting the Process, G. D. Nelson 610
Aluminum Castings, Problems in Finishing, F. L. Mickelson 1319
Aluminum Corrosion Test, Ford Anodized—FACT, J. Stone, H. A. Tuttle, and H. N. Bogart 877
Aluminum, Dilute Zincating Solutions for Plating on, E. B. Saubestre and J. L. Morico 899
Aluminum, Properties of Electroformed, F. J. Schmidt and I. J. Hess 229
Aluminum, Sealing of Chromic Acid Anodized, H. Geduld 1002
Analysis of Phosphoric-Sulfuric Mild Steel Etching Baths, G. D. Nelson and F. B. Clarke 474
Anodes, The Effect of Sulfur, Phosphorus and Silicon Additives on the Activity and Type of Corrosion of Nickel, G. A. DiBari 1440
Anodized Aluminum Corrosion Test, Ford—FACT, J. Stone, H. A. Tuttle, and H. N. Bogart 877
Anodizing Process, Quality and Cost Improvement in the Aluminum Bright. III. The Recovery of Phosphoric Acid from Aluminum Bright Dip Rinse Solution, G. D. Nelson, C. P. Schumacher, W. J. Shortreed, and J. T. Sommerfeld .. 72
Antler, M.
New Developments in the Surface Science of Electric Contacts 1431
Antonov, A. Ya., S. S. Kruglikov, N. T. Kudryavtsev, and R. P. Sobolev
Influence of Periodic Interruptions of Current on the Electrodeposition of Nickel from Leveling Solutions 78
Apathy the Destroyer, G. W. Cavanaugh (Editorial) 7
Application of "Plating Simulation" to Chromium Plating, J. J. Christie 587
Arnold, S. M.
Repressing the Growth of Tin Whiskers 96
Art Form, Electroplating—A New, D. G. Foulke 824

ASTM

Meeting of the ASTM Committee B-8, E. B. Saubestre 522

AUTHORS

Alford, E. F. 482
Antler, M. 1456
Arnold, S. M. 113
Baeyens, Dr. P. 621
Baldwin, P. C. 1456
Barnes, G. E. 1127
Basco, R. P. 112, 338, 1008
Beck, R. U. 910
Bedetti, F. V. 338
Bednar, J. 621
Ben, M. 481
Blum, W. 353
Bogart, H. N. 910
Brooks, W. D. 482
Brown, G. W. 787
Brown L. J. 238
Cabrinety, L. P. 338
Camp, E. K. 338
Carlin, F. X. 1237
Caropreso, F. E. 1456
Catchmark, A. 830
Chapdelaine, E. G. 481
Chiarenzelli, R. V. 338
Christie, J. J. 621, 1238
Clarke, F. B. 482
Conrad, F. J. 786
Dancy, W. H. 622
DiBari, G. A. 1457
Dingley, W. 621
Dollman, G. W. 1456
Doty, W. R. 1126
Easton, J. K. 1346
Endicott, D. W. 112
Farrell, M. A. 1127
Fedot'ev, N. P. 338
Foulke, D. G. 1238
Garte, S. M. 1346
Garwood, W. S. 1346
Geduld, H. 1009
Goldstein, D. 1456
Graham, A. K. 1237
Greenall, G. J. 238
Griffin, J. L. 238
Hagstrom, R. A. 338
Heiman, S. 830
Hess, I. J. 239
Hill, F. N. 787
Hogya, B. J. 621, 1457
Jacobus, W. N. Jr. 114
Jayakrishnan, P. 1457
Jones, M. H. 1009
Judge, J. S. 481
Kenez, M. G. 1009
Kenna, B. T. 786
Kessler, R. B. 1126
Knap, J. E. 787
Knapp, J. R. Jr. 112

INDEX TO PLATING VOL. 53, 1966

A

About Two Microstructural Features of Electrodeposits, R. Weil and W. N. Jacobus Jr. 102
Accelerated Electrolytic Corrosion Test and a Corrosion Analysis Procedure for the Nickel-Chromium Plating System—Part I., R. L. Saur and R. P. Basco 35

ADHESION

Adhesion of Chromium Deposited on Steel, Influence of Etch Bath on the, W. H. Dancy and A. Zavarella 618
Adhesion of Plated Coatings on Selected Areas of Aluminum Alloys, Improving Adhesion of, M. Ben and W. D. Brooks 480
Adhesion to Decorative Trim, Paint, W. S. Garwood 1323

AES

AES Educational Tour to South America 1024, 1250
AES Research Project No. 23—Initial Stages of Nickel Deposition: I. The Watts Bath, M. H. Jones and M. G. Kenez .. 995
AES Educational Tour to South America 1131
AES Expands and Diversifies Its Publication Features, W. H. Safranek (Editorial) 1291
AES Research Project No. 12—Cleaning and Preparation of Metals Prior to Electroplating XVII. The Effect of Stearic Acid Films on the Overpotential for Hydrogen Evolution, M. A. Farrell and H. B. Linford 1110
AES Research Project No. 21—Physical and Mechanical Properties of Electrodeposited Copper II. The Sulfate Bath, V. A. Lamb and D. R. Valentine 86
AES-Sponsored Research, Changing Nature of, D. R. Turner (Editorial) 283
Annual Report, 1965–1966 633
Branch Directory 1366
Colorful Dallas Beckons AES for '67 804
Constitution and Bylaws 506
Dallas Convention Program Shaping Up 1470
Dallas—Shiny, New AES Convention City 1176
Educational Program, 53rd AES Annual Convention 487, 626
Fifty-Third AES Convention in Miami Beach Sponsored by Dixie Regional Council with Southeastern Branch as Host ... 1013
Financial Report 1246
Four Society Papers Win Six Awards 920
Linford, Henry B.—AES Scientific Achievement Award Recipient .. 920
Miami Beach: City of Color and Contrast, L. R. Diveley 1132
Nominees for National Office and Board of Directors 241
Plating in the Electronics Industry Symposium Program 1560
Profiles of Nominees for AES Second Vice President 490
Profiles of Nominees for Board of Directors 490
Program, AES 53rd Annual Convention 625
Quarterly Report of AES Vice Chairman for Research, M. M. Beckwith 354
Quarterly Research Report, M. M. Beckwith 1011
Reports of 1965–66 Board and Committee Chairmen and Liaison Representatives to Other Societies 800
Research Activities of the American Electroplaters' Society, W. Blum 341
Tentative Program, 53rd AES Annual Convention 486
Airless Spray Painting, J. H. Reichenbach 991
Airline Plating Forum, Second, Keynote Address, T. P. Murphy 705
Alford, E. F.
Electrodeposition of Paint 478

ALUMINUM

Aluminum Alloys, Chemical Composition of Sulfuric Acid Anodic Films on, R. C. Spooner 451
Aluminum Alloys, Electroplating on, D. W. Levinson and L. F. Mondolfo 986
Aluminum Alloys, Improving Adhesion of Plated Coatings on Selected Areas of, M. Ben and W. D. Brooks 480
Aluminum Bright Anodizing Process, Quality and Cost Improvement in the. III, The Recovery of Phosphoric Acid from Aluminum Bright Dip Rinse Solution, G. D. Nelson, C. P. Schumacher, W. J. Shortreed, and J. T. Sommerfeld 72
Aluminum Bright Anodizing Process, Quality and Cost Improvement in the. IV. Trouble-Shooting the Process, G. D. Nelson 610
Aluminum Castings, Problems in Finishing, F. L. Mickelson 1319
Aluminum Corrosion Test, Ford Anodized—FACT, J. Stone, H. A. Tuttle, and H. N. Bogart 877
Aluminum, Dilute Zincating Solutions for Plating on, E. B. Saubestre and J. L. Morico 899
Aluminum, Properties of Electroformed, F. J. Schmidt and I. J. Hess 229
Aluminum, Sealing of Chromic Acid Anodized, H. Geduld 1002
Analysis of Phosphoric-Sulfuric Mild Steel Etching Baths, G. D. Nelson and F. B. Clarke 474
Anodes, The Effect of Sulfur, Phosphorus and Silicon Additives on the Activity and Type of Corrosion of Nickel, G. A. DiBari 1440
Anodized Aluminum Corrosion Test, Ford—FACT, J. Stone, H. A. Tuttle, and H. N. Bogart 877
Anodizing Process, Quality and Cost Improvement in the Aluminum Bright. III. The Recovery of Phosphoric Acid from Aluminum Bright Dip Rinse Solution, G. D. Nelson, C. P. Schumacher, W. J. Shortreed, and J. T. Sommerfeld .. 72
Antler, M.
New Developments in the Surface Science of Electric Contacts 1431
Antonov, A. Ya., S. S. Kruglikov, N. T. Kudryavtsev, and R. P. Sobolev
Influence of Periodic Interruptions of Current on the Electrodeposition of Nickel from Leveling Solutions 78
Apathy the Destroyer, G. W. Cavanaugh (Editorial) 7
Application of "Plating Simulation" to Chromium Plating, J. J. Christie 587
Arnold, S. M.
Repressing the Growth of Tin Whiskers 96
Art Form, Electroplating—A New, D. G. Foulke 824

ASTM

Meeting of the ASTM Committee B-8, E. B. Saubestre 522

AUTHORS

Alford, E. F. 482
Antler, M. 1456
Arnold, S. M. 113
Baeyens, Dr. P. 621
Baldwin, P. C. 1456
Barnes, G. E. 1127
Basco, R. P. 112, 338, 1008
Beck, R. U. 910
Bedetti, F. V. 338
Bednar, J. 621
Ben, M. 481
Blum, W. 353
Bogart, H. N. 910
Brooks, W. D. 482
Brown, G. W. 787
Brown L. J. 238
Cabrinety, L. P. 338
Camp, E. K. 338
Carlin, F. X. 1237
Caropreso, F. E. 1456
Catchmark, A. 830
Chapdelaine, E. G. 481
Chiarenzelli, R. V. 338
Christie, J. J. 621, 1238
Clarke, F. B. 482
Conrad, F. J. 786
Dancy, W. H. 622
DiBari, G. A. 1457
Dingley, W. 621
Dollman, G. W. 1456
Doty, W. R. 1126
Easton, J. K. 1346
Endicott, D. W. 112
Farrell, M. A. 1127
Fedot'ev, N. P. 338
Foulke, D. G. 1238
Garte, S. M. 1346
Garwood, W. S. 1346
Geduld, H. 1009
Goldstein, D. 1456
Graham, A. K. 1237
Greenall, G. J. 238
Griffin, J. L. 238
Hagstrom, R. A. 338
Heiman, S. 830
Hess, I. J. 239
Hill, F. N. 787
Hogya, B. J. 621, 1457
Jacobus, W. N. Jr. 114
Jayakrishnan, P. 1457
Jones, M. H. 1009
Judge, J. S. 481
Kenez, M. G. 1009
Kenna, B. T. 786
Kessler, R. B. 1126
Knap, J. E. 787
Knapp, J. R. Jr. 112

Knoedler, A. 786
Kruglikov, S. S. 113
Kudryavtsev, N. T. 113, 910
Lamb, V. A. 113
Levinson, D. W. 1008
Linford, H. B. 1127
Lloyd, D. A. 621
Marinaro, A. T. 1238
Marti, J. L. 112
Mickelson, F. L. 1346
Miller, G. A. 113
Mondolfo, L. F. 1008
Morico, J. L. 911
Morrison, J. R. 481
Nechaev, E. A. 910
Nelson, G. D. 112, 482, 621
Nobel, F. I. 1126
Noonan, H. J. 481
Olivero, A. 786
Ostrow, B. D. 1126
Parthasaradhy, N. V. 1457
Pech, W. 238
Pesetsky, B. 787
Pfeiffer, W. 786
Pinkerton, H. L. 1238
Radimer, K. J. 621, 1456
Rajagopalan, S. R. 1457
Raub, E. 787
Reichenbach, J. H. 1009
Rogers, R. R. 621
Rothschild, B. F. 481
Safranek, W. H. 1237
Saubestre, E. B. 910
Saur, R. L. 112, 338, 1008, 1127
Schmidt, F. J. 239
Schumacher, B. W. 1238
Schumacher, C. P. 112
Searles, H. 238
Shortreed, W. J. 113
Siwinski, G. W. 1456
Sobolev, R. P. 113
Sommerfeld, J. T. 113
Speliotis, D. E. 481
Spooner, R. C. 481
Stephenson, R. 112
Stephenson, W. B. Jr. 238
Stone, J. 910
Thomson, D. W. 1126
Tuttle, H. A. 910
Valentine, D. R. 113
Villata, E. 786
Wade, W. H. 787
Walton, R. F. 238
Weber, A. 112
Weekly, C. C. 113
Weil, R. 114
Weiner, R. 911
Whitfield, C. E. Sr. 1009
Whittington, C. M. 238
Zavarella, A. 622

Automatic Machines for Electroplating, Program-Controlled Fully, W. Pech 193

B

Baeyens, P.
Electroformed Molds and Dies 591

Baldwin, P. C.
Colorimetric Control Procedures for Proprietary Gold Plating Solutions 1450

Barnes, G. E.
Disposal and Recovery of Electroplating Wastes 1115

Barrel Plating, Factors That Influence Gold Metal Distribution in, F. I. Nobel, B. D. Ostrow, R. B. Kessler, and D. W. Thomson 1099

Barrel Plating Solutions Through the Use of the Rotary Cathode Plating Test Cell, Examination of, E. G. Chapdelaine 471

Basco, R. P. and R. L. Saur
Accelerated Electrolytic Corrosion Test and a Corrosion Analysis Procedure for the Nickel-Chromium Plating System, Part I.... 35

Correlation of "EC" and CASS Tests to Service Using Duplex Nickel Systems 320
Corrosion of Triplex Nickel Systems in Service and in the EC and CASS Tests 981

Beck, R. U., N. T. Kudryavtsev, and E. A. Nechaev
Electrodeposition of Silver from Cyanide Solutions at a High Current Density 889

Bedetti, F. V. and R. V. Chiarenzelli
Porosity Testing of Electroplated Gold in Gelled Media 305

Bednar, J., W. Dingley, and R. R. Rogers
Stable Copper Cyanide Plating Baths 602

Ben, M., and W. D. Brooks
Improving Adhesion of Plated Coatings on Selected Areas of Aluminum Alloys 480

Beyer, S. J.
Make Your Deposit Now (Editorial) 1069

Bibliography of Metal Finishing Wastes for 1965, D. G. Foulke.... 1459

Blum, W.
Research Activities of the American Electroplaters' Society 341

Bogart, H. N., J. Stone and H. A. Tuttle
Ford Anodized Aluminum Corrosion Test—FACT 877

BOOK REVIEWS

Chemical Surface Treatments of Metals, W. Wiederholt 427
Contributions to the Theory of Chromium Plating, R. Vishomirskis, U. Matulis, M. Mitskus, V. Petrauskas 1199
Dictionary of Metallurgy, D. Birchon 178
Electrofinishing, M. A. Brimi and J. R. Luck 177
Electropainting, R. L. Yeates 744
Galvanisieren von Kunstoffen (Electroplating on Plastics), G. Müller. 1242
New Ways of Working Metals, D. Fishlock and K. W. Hards 427
Technology of Tinplate, W. E. Hoare, E. S. Hedges, and B. T. K. Barry 681
Theory and Practice of Chromium Electroplating, A. T. Vagramyan and N. T. Kudryavtsev 1199

Branch Presidents Aren't Born, R. F. Ledford, (Editorial) 541

Bromide Ion on Stress in a Nickel Sulfamate Bath, Effect of, H. Searles.. 204

Brooks, W. D. and M. Ben
Improving Adhesion of Plated Coatings on Selected Areas of Aluminum Alloys 480

Brown, G. W. and W. H. Wade
System for Numerical Evaluation of the Solderability of Lead Wires.. 783

Brown, L. J.
Silicates as Cleaners in the Production of Tinplate 225

C

Cabrinety, L. P. and R. A. Hagstrom
Saturn V Guidance System Protective Finish 331

Calculation of the Maximum Current Density for Corroding Specimens in the EC Test, R. L. Saur 1124

Camp, E. K.
Tarnishing of Thin Rhenium Deposits on Nickel: Effect of Plating Process Anions and Ultrasonics 318

Carlin, F. X.
High-Speed Plating of Industrial Nickel Coatings 1205

Caropreso, F. E., K. J. Radimer, D. Goldstein, G. W. Siwinski, and B. J. Hogya
Recovery of Persulfate from Printed Circuit Etchants 1445

CASS Tests, Corrosion of Triplex Nickel Systems in Service and in the EC and, R. L. Saur and R. P. Basco 981

CASS Tests to Service Using Duplex Nickel Systems, Correlation of "EC" and, R. L. Saur and R. P. Basco 320

Catchmark, A. and S. Heiman
Some Aspects of Plating Research in Japan—Visits to A Few University Laboratories 828

Cavanaugh, G. S.
Apathy the Destroyer (Editorial).. 7
Reaching New Horizons (Editorial) 853
Peace on Earth (Editorial) 1407

Chapdelaine, E. G.
Examination of Barrel Plating Solutions Through the Use of the Rotary Cathode Plating Test Cell.. 471

Chemical Composition of Sulfuric Acid Anodic Films on Aluminum Alloys, R. C. Spooner 451

Chiarenzelli, R. V. and F. V. Bedetti
Porosity Testing of Electroplated Gold in Gelled Media 305

Chloride Etching Baths, Rapid Spectrophotometric Determination of Copper in Ferric, F. J. Conrad and B. T. Kenna 763

Christie, J. J.
Application of "Plating Simulation" to Chromium Plating 587
Predicting Current Distribution on a Cathode: "Plating Simulation" vs Mathematics 1207

Chromic Acid Anodized Aluminum, Sealing of, H. Geduld 1002

CHROMIUM

Chromium Deposited on Steel, Influence of Etch Bath on the Adhesion of Chromium, W. H. Dancy Jr. and A. Zavarella 618
Chromium Electrodeposition as Affected by a Variety of Possible Catalysts, Experimental, J. L. Griffin 196
Chromium Plate, Vapor Plating with Dicumenechromium: Preparation and Properties of the, J. E. Knap, B. Pesetsky and F. N. Hill 772
Chromium Plating, Application of "Plating Simulation" to, J. J. Christie 587

Clarke, F. B. and G. D. Nelson
Analysis of Phosphoric-Sulfuric Mild Steel Etching Baths 474

Cleaners in the Production of Tinplate, Silicates as, L. J. Brown.... 225

Cleaning and Preparation of Metals Prior to Electroplating. XVII. The Effect of Stearic Acid Films on the Overpotential for Hydrogen Evolution, M. A. Farrell and H. B. Linford 1110

Cobalt-Nickel-Phosphorus, Flexible Recording Surfaces of Electrodeposited, J. S. Judge, J. R. Morrison, and D. E. Speliotis 441

Colorimetric Control Procedures for Proprietary Gold Plating Solutions, P. C. Baldwin 1450

Computers and Plating, W. D. Mogerman 1351

Conrad, F. J. and B. T. Kenna
Rapid Spectrophotometric Determination of Copper in Ferric Chloride Etching Baths 763

Contact Resistance of Electroplated Materials, Effect of Type and Po-

rosity of Gold Deposits on the, R. F. Walton 209
Contacts, New Developments in the Surface Science of Electric, M. Antler 1431

CONVENTION PAPERS

AES Research Project No. 12—Cleaning and Preparation of Metals Prior to Electroplating. XVII. The Effect of Stearic Acid Films on the Overpotential for Hydrogen Evolution, M. A. Farrell and H. B. Linford 1110
AES Research Project No. 23—Initial Stages of Nickel Deposition: I. The Watts Bath, M. H. Jones and M. G. Kenez 995
Analysis of Phosphoric-Sulfuric Mild Steel Etching Baths, G. D. Nelson and F. B. Clarke 474
Determination of the Porosity of Gold Electrodeposits by Quantitative Electrography, S. M. Garte 1331
Dilute Zincating Solutions for Plating on Aluminum, E. B. Saubestre and J. L. Morico 899
Dollars and Sense about Plating Waste Treatment and Water Conservation, A. K. Graham and H. L. Pinkerton 1222
Effect of Substrate Roughness on the Porosity of Gold Electrodeposits, S. M. Garte 1335
Electrolytic Decomposition of Concentrated Cyanide Plating Wastes, J. K. Easton 1340
Factors that Influence Gold Metal Distribution in Barrel Plating, F. I. Nobel, B. D. Ostrow, R. B. Kessler, and D. W. Thomson 1099
High-Speed Plating of Industrial Nickel Coatings, F. X. Carlin ... 1203
Paint Adhesion to Decorative Trim, W. S. Garwood 1323
Pollution Abatement—The Masters' Electro-Plating Association and the National Association of Metal Finishers, A. T. Marinaro. 1230
Problems in Finishing Aluminum Castings, F. L. Mickelson 1319
Quality and Cost Improvement in the Aluminum Bright Anodizing Process. IV. Trouble-Shooting the Process, G. D. Nelson 610
Sealing of Chromic Acid Anodized Aluminum, H. Geduld 1002
Stable Copper Cyanide Plating Baths, W. Dingley, J. Bednar, and R. R. Rogers 602
System for Numerical Evaluation of the Solderability of Lead Wires, W. H. Wade and G. W. Brown .. 783
Vapor Plating with Dicumenechromium: Preparation and Properties of the Chromium Plate, J. E. Knap, B. Pesetsky, and F. N. Hill 772
Waste Treatment and the Metal Finishing Industry, D. G. Foulke 1217

COPPER

Copper Cyanide Plating Baths, Stable, W. Dingley, J. Bednar, and R. R. Rogers 602
Copper Electroforming of Wave Guides, Some Experiences in, P. Jayakrishnan, N. V. Parthasaradhy, and S. R. Rajagopalan 1453
Copper in Ferric Chloride Etching Baths, Rapid Spectrophotometric Determination of, F. J. Conrad and B. T. Kenna 763
Copper, Physical and Mechanical Properties of Electrodeposited, II. The Sulfate Bath (AES Research Project No. 21), V. A. Lamb and D. R. Valentine 86
Correlation of "EC" and CASS Tests to Service Using Duplex Nickel Systems, R. L. Saur and R. P. Basco 320

CORROSION

Corroding Specimens in the EC Test, Calculation of the Maximum Current Density for, R. L. Saur 1124
Corrosion of Nickel Anodes, The Effect of Sulfur, Phosphorus and Silicon Additives on the Activity and Type of, G. A. DiBari 1440
Corrosion Path in Bright Nickel, W. R. Doty 1105
Corrosion of Triplex Nickel Systems in Service and in the EC and CASS Tests, R. L. Saur and R. P. Basco 981
Corrosion Test and a Corrosion Analysis Procedure for the Nickel-Chromium Plating System, Accelerated Electrolytic, Part I., R. L. Saur and R. P. Basco 35
Corrosion Test, Ford Anodized Aluminum—FACT, J. Stone, H. A. Tuttle and H. N. Bogart 877
Current Density for Corroding Specimens in the EC Test, Calculation of the Maximum, R. L. Saur 1124
Current Distribution on a Cathode: "Plating Simulation" vs Mathematics, Predicting, J. J. Christie ... 1207
Curry, J. J.
Regulations for Industrial Waste in State of Connecticut 659

CYANIDE

Cyanide Plating Baths, Stable Copper, W. Dingley, J. Bednar, and R. R. Rogers 602
Cyanide Plating Wastes, Electrolytic Decomposition of Concentrated, J. K. Easton 1340
Cyanide Solutions at a High Current Density, Electrodeposition of Silver from, N. T. Kudryavtsev, R. U. Beck, and E. A. Nechaev 889
Cyanide Zinc Plating Solutions, Sodium Cyanide Determination in, A. Olivero and E. Villata 770
Cyanoaurate (III) Solutions and Some Characteristics of the Cyanoaurate Complex, Gold Electrodeposits from, A. Knoedler, E. Raub, and W. Pfeiffer 765

D

Dancy, W. H. Jr. and A. Zavarella
Influence of Etch Bath on The Adhesion of Chromium Deposited on Steel 618
Determination of Certain Additives in Plating Baths. Determination of Peptone in Solder Baths, G. W. Dollman 1448
Determination of the Porosity of Gold Electrodeposits by Quantitative Electrography, S. M. Garte 1331
Development and Utilization of a High Strength Alloy for Electroforming, W. B. Stephenson Jr. 183
DiBari, G. A.
Effect of Sulfur, Phosphorus and Silicon Additives on the Activity and Type of Corrosion of Nickel Anodes 1440
Dicumenechromium: Preparation and Properties of the Chromium Plate, Vapor Plating with, J. E. Knap, B. Pesetsky, and F. N. Hill. 772
Dies, Electroformed Molds and, P. Baeyens 591
Dilute Zincating Solutions for Plating on Aluminum, E. B. Saubestre and J. L. Morico 899
Dingley, W., J. Bednar, and R. R. Rogers
Stable Copper Cyanide Plating Baths 602
Diveley, L. L.
Scope (Editorial) 733

DISCUSSIONS

Adhesion of Chromium and Other Deposits to Steel, W. H. Dancy and A. Zavarella 620
Corrosion of Triplex Nickel Systems in Service and in the EC and CASS Tests, R. L. Saur and R. P. Basco 1346
Dilute Zincating Solutions for Plating on Aluminum, E. B. Saubestre and J. L. Morico 1237
Prediction of Nickel Plate Distribution by Plating Simulation, J. J. Christie and J. D. Thomas and The Application of "Plating Simulation" to Chromium Plating, J. J. Christie 1125
Disposal and Recovery of Electroplating Wastes, G. E. Barnes 1115
Dollars and Sense about Plating Waste Treatment and Water Conservation, A. K. Graham and H. L. Pinkerton 1222
Dollman, G. W.
Determination of Certain Additives in Plating Baths. Determination of Peptone in Solder Baths 1448
Doty, W. R.
Corrosion Path in Bright Nickel ... 1105
Dubpernell, G.
A Plating Electrochemist's First Trip Abroad 702
Duplex Nickel Systems, Correlation of "EC" and CASS Tests to Service Using, R. L. Saur and R. P. Basco .. 320

E

Easton, J. K.
Electrolytic Decomposition of Concentrated Cyanide Plating Wastes 1340

EC TEST

EC and CASS Tests, Corrosion of Triplex Nickel Systems in Service and in the, R. L. Saur and R. P. Basco 981
EC and CASS Tests to Service Using Duplex Nickel Systems, Correlation of, R. L. Saur and R. P. Basco 320
EC Test, Calculation of the Maximum Current Density for Corroding Specimens in the, R. L. Saur 1124

EDITORIALS

AES Expands and Diversifies Its Publication Features, W. H. Safranek 1291
Apathy the Destroyer, G. W. Cavanaugh 7
Branch Presidents Aren't Born, R. F. Ledford 541
Changing Nature of AES-Sponsored Research, D. R. Turner ... 283
Make Your Deposit Now, S. J. Beyer 1069
Nominating Committee, E. E. Oberland 155
Peace on Earth, G. W. Cavanaugh. 1407
Philosophy of Work, A, A. G. Gray. 1175
Reaching New Horizons, G. W. Cavanaugh 853
Scope, L. L. Diveley 733
Training, D. A. Swalheim 403

What Is Public Relations?, G. E. Parisho ... 957
Effect of Board Thickness to Hole Diameter Ratio on Plating of Printed Circuits, B. F. Rothschild ... 437
Effect of Bromide Ion on Stress in a Nickel Sulfamate Bath, H. Searles ... 204
Effect of Some Variables upon Internal Stress of Nickel as Deposited from Sulfamate Electrolytes, J. L. Marti ... 61
Effect of Substrate Roughness on the Porosity of Gold Electrodeposits, S. M. Garte ... 1335
Effect of Sulfur, Phosphorus and Silicon Additives on the Activity and Type of Corrosion of Nickel Anodes, G. A. DiBari ... 1440
Effect of Type and Porosity of Gold Deposits on the Contact Resistance of Electroplated Materials, R. F. Walton ... 209
Electric Contacts, New Developments in the Surface Science of, M. Antler ... 1431

ELECTRODEPOSITION

Electrodeposited Metals, Physical and Mechanical Properties of, N. P. Fedot'ev ... 309
Electrodeposition of Nickel-Cobalt Alloy: Operating Variables and Physical Properties of the Deposits, D. W. Endicott and J. R. Knapp Jr. ... 43
Electrodeposition of Paint, E. F. Alford ... 478
Electrodeposition of Silver from Cyanide Solutions at a High Current Density, N. T. Kudryavtsev, R. U. Beck, and E. A. Nechaev ... 889
Electrodeposits, About Two Microstructural Features of, R. Weil and W. N. Jacobus Jr. ... 102

ELECTROFORMING

Electroformed Aluminum, Properties of, F. J. Schmidt and I. J. Hess ... 229
Electroformed Molds and Dies, P. Baeyens ... 591
Electroforming, Development and Utilization of a High Strength Alloy for, W. B. Stephenson Jr. ... 183
Electroforming for Fabricating Structures, A Survey of, W. H. Safranek ... 1211
Electrographic Determination of Porosity in Gold Electrodeposits, H. J. Noonan ... 461
Electrolytic Decomposition of Concentrated Cyanide Plating Wastes, J. K. Easton ... 1340
Electron Beam Thickness Gage on Multi-Layered Coatings, Use of the, B. W. Schumacher ... 1235
Electroplating—A New Art Form, D. G. Foulke ... 824
Electroplating on Aluminum Alloys, D. W. Levinson and L. F. Mondolfo 986
Elliott, D.
Wire Plating ... 335
Endicott, D. W. and J. R. Knapp Jr.
Electrodeposition of Nickel-Cobalt Alloy: Operating Variables and Physical Properties of the Deposits ... 43

ETCHING

Etchants, Recovery of Persulfate from Printed Circuit, K. J. Radimer, F. E. Caropreso, D. Goldstein, G. W. Siwinski, and B. J. Hogya ... 1445
Etch Bath on the Adhesion of Chromium Deposited on Steel, Influence of, W. H. Dancy Jr. and A. Zavarella ... 618
Etching Baths, Analysis of Phosphoric-Sulfuric Mild Steel, G. D. Nelson and F. B. Clarke ... 474
Etching Baths, Rapid Spectrophotometric Determination of Copper in Ferric Chloride, F. J. Conrad and B. T. Kenna ... 763
Etching of Printed Circuits, Stepwise Countercurrent, K. J. Radimer, D. A. Lloyd, and B. J. Hogya 598
Examination of Barrel Plating Solutions Through the Use of the Rotary Cathode Plating Test Cell, E. G. Chapdelaine ... 471
Experimental Chromium Electrodeposition as Affected by a Variety of Possible Catalysts, J. L. Griffin ... 196

F

Fabricating Structures, A Survey of Electroforming for, W. H. Safranek. 1211
Factors That Influence Gold Metal Distribution in Barrel Plating, F. I. Nobel, B. D. Ostrow, R. B. Kessler, and D. W. Thomson ... 1099
Farrell, M. A. and H. B. Linford
Cleaning and Preparation of Metals Prior to Electroplating. XVII. The Effect of Stearic Acid Films on the Overpotential for Hydrogen Evolution ... 1110
Federal Aspects of Industrial Waste Disposal, A. A. Ribicoff ... 657
Fedot'ev, N. P.
Physical and Mechanical Properties of Electrodeposited Metals ... 309
Finish, Saturn V Guidance System Protective, L. P. Cabrinety and R. A. Hagstrom ... 331
Flexible Recording Surfaces of Electrodeposited Cobalt-Nickel-Phosphorus, J. S. Judge, J. R. Morrison, and D. E. Speliotis ... 441
Ford Anodized Aluminum Corrosion Test—FACT, J. Stone, H. A. Tuttle, and H. N. Bogart ... 877
Foulke, D. G.
Electroplating—A New Art Form .. 824

FOREIGN FINISHING REPORTS

United Kingdom, T. E. Such ... 235, 1455
Foulke, D. G.
Bibliography of Metal Finishing Wastes for 1965 ... 1459
Waste Treatment and the Metal Finishing Industry ... 1217

G

Gage on Multi-Layered Coatings, Use of the Electron Beam Thickness, B. W. Schumacher ... 1235
Garte, S. M.
Determination of the Porosity of Gold Electrodeposits by Quantitative Electrography ... 1331
Effect of Substrate Roughness on the Porosity of Gold Electrodeposits ... 1335
Garwood, W. S.
Paint Adhesion to Decorative Trim. 1323
Geduld, H.
Sealing of Chromic Acid Anodized Aluminum ... 1002
Gelled Media, Porosity Testing of Electroplated Gold in, F. V. Bedetti and R. V. Chiarenzelli ... 305
Glamorous Time—A Look Back, K. G. Soderberg ... 1262

GOLD

Gold Deposits on the Contact Resistance of Electroplated Materials, Effect of Type and Porosity of, R. F. Walton ... 209
Gold Electrodeposits by Quantitative Electrography, Determination of the Porosity of, S. M. Garte ... 1331
Gold Electrodeposits, Effect of Substrate Roughness on the Porosity of, S. M. Garte ... 1335
Gold Electrodeposits, Electrographic Determination of Porosity in, H. J. Noonan ... 461
Gold Electrodeposits from Cyanoaurate (III) Solutions and Some Characteristics of the Cyanoaurate Complex, A. Knoedler, E. Raub and W. Pfeiffer ... 765
Gold in Gelled Media, Porosity Testing of Electroplated, F. V. Bedetti and R. V. Chiarenzelli ... 305
Gold in Plating Baths, Rapid Gravimetric Determination of, G. A. Miller ... 100
Gold Metal Distribution in Barrel Plating, Factors That Influence, F. I. Nobel, B. D. Ostrow, R. B. Kessler, and D. W. Thomson ... 1099
Gold Plating Solutions, Colorimetric Control Procedures for Proprietary, P. C. Baldwin ... 1450
Goldstein, D., K. J. Radimer, F. E. Caropreso, G. W. Siwinski and B. J. Hogya
Recovery of Persulfate from Printed Circuit Etchants ... 1445
Graham, A. K. and H. L. Pinkerton
Dollars and Sense about Plating Waste Treatment and Water Conservation ... 1222
Gray, A. G.
A Philosophy of Work (Editorial) ... 1175
Greenall, G. J. and C. M. Whittington
Metallic Impurities in Nickel Plating Solutions ... 217
Griffin, J. L.
Experimental Chromium Electrodeposition as Affected by a Variety of Possible Catalysts ... 196
Guide to Authors of Papers for PLATING ... 16, 339, 912, 1026, 1455

H

Hagstrom, R. A. and L. P. Cabrinety
Saturn V Guidance System Protective Finish ... 331
Hardness and Abrasion Resistance of Bright Silver Electrodeposits, R. Weiner ... 894
Heiman, S.
Some Production Plating Problems and How They Were Solved, Part III ... 110
Part IV ... 333
Part V ... 615
Part VII ... 1122
Part VIII ... 1343
Heiman, S. and S. J. Beyer
Some Production Plating Problems and How They Were Solved, Part VI ... 905
Heiman, S. and A. Catchmark
Some Aspects of Plating Research in Japan—Visits to a Few University Laboratories ... 828
Hess, I. J. and F. J. Schmidt
Properties of Electroformed Aluminum ... 229
High-Speed Plating of Industrial Nickel Coatings, F. X. Carlin ... 1203
Hill, F. N., J. E. Knap, and B. Pesetsky
Vapor Plating with Dicumenechromium: Preparation and Properties of the Chromium Plate ... 772
Hogya, B. J., K. J. Radimer, F. E. Caropreso, D. Goldstein, and G. W. Siwinski
Recovery of Persulfate from Printed Circuit Etchants ... 1445

Hogya, B. J., K. J. Radimer, and D. A. Lloyd
Stepwise Countercurrent Etching of Printed Circuits 598
Hydrogen Evolution, The Effect of Stearic Acid Films on the Overpotential for (Part XVII, Cleaning and Preparation of Metals Prior to Electroplating), M. A. Farrell and H. B. Linford 1110

I

"I'd Like to Know" Plating Problems Forum 326
Improved Productivity of Vacuum Metalizers through Simple Maintenance, H. B. Hebble Jr. 1048
Improving Adhesion of Plated Coatings on Selected Areas of Aluminum Alloys, M. Ben and W. D. Brooks 480
Influence of Periodic Interruptions of Current on the Electrodeposition of Nickel from Leveling Solutions, S. S. Kruglikov, N. T. Kudryavtsev, R. P. Sobolev, and A. Y. Antonov 78
Initial Stages of Nickel Deposition: I. The Watts Bath, M. H. Jones and M. G. Kenez 995

J

Jacobus, W. N. Jr. and R. Weil
About Two Microstructural Features of Electrodeposits 102
Japan, Some Aspects of Plating Research in—Visits to a Few University Laboratories, S. Heiman and A. Catchmark 828
Jayakrishnan, P., N. V. Parthasaradhy, and S. R. Rajagopalan
Some Experiences in Copper Electroforming of Wave Guides 1453
Jones, M. H. and M. G. Kenez
Initial Stages of Nickel Deposition: I. The Watts Bath 995
Judge, J. S., J. R. Morrison, and D. E. Speliotis
Flexible Recording Surfaces of Electro deposited Cobalt-Nickel-Phosphorus 441

K

Kenez, M. G. and M. H. Jones
Initial Stages of Nickel Deposition: I. The Watts Bath 995
Kenna, B. T. and F. J. Conrad
Rapid Spectrophotometric Determination of Copper in Ferric Chloride Etching Baths 763
Kessler, R. B., F. I. Nobel, B. D. Ostrow, and D. W. Thomson
Factors That Influence Gold Metal Distribution in Barrel Plating ... 1099
Keynote Address, Second Airline Plating Forum, T. P. Murphy 705
Knap, J. E., B. Pesetsky, and F. N. Hill
Vapor Plating with Dicumenechromium: Preparation and Properties of the Chromium Plate 772
Knapp, J. R. Jr. and D. W. Endicott
Electrodeposition of Nickel-Cobalt Alloy: Operating Variables and Physical Properties of the Deposits 43
Knoedler, A., E. Raub, and W. Pfeiffer
Gold Electrodeposits from Cyanoaurate (III) Solutions and Some Characteristics of the Cyanoaurate Complex 765
Kruglikov, S. S., N. T Kudryavtsev, R. P. Sobolev, and A. Y. Antonov
Influence of Periodic Interruptions of Current on the Electrodeposition of Nickel from Leveling Solutions 78
Kudryavtsev, N. T., R. P. Sobolev, A. Y. Antonov, and S. S. Kruglikov
Influence of Periodic Interruptions of Current on the Electrodeposition of Nickel from Leveling Solutions 78
Kudryavtsev, N. T., R. U. Beck, and E. A. Nechaev
Electrodeposition of Silver from Cyanide Solutions at a High Current Density 889

L

Lamb, V. A. and D. R. Valentine
AES Research Project No. 21—Physical and Mechanical Properties of Electrodeposited Copper II. The Sulfate Bath 86
Lead Wires, A System for Numerical Evaluation of the Solderability of, W. H. Wade and G. W. Brown 783
Ledford, R. F.
Branch Presidents Aren't Born (Editorial) 541
Levinson, D. W. and L. F. Mondolfo
Electroplating on Aluminum Alloys 986
Linford, H. B. and M. A. Farrell
Cleaning and Preparation of Metals Prior to Electroplating. XVII. The Effect of Stearic Acid Films on the Overpotential for Hydrogen Evolution 1110
Lloyd, D. A., B. J. Hogya, and K. J. Radimer
Stepwise Countercurrent Etching of Printed Circuits 598
Logozzo, A. W. and E. E. Oberland
Report on the NAMF-AES Trade Tour to the Orient 694

M

Make Your Deposit Now, S. J. Beyer, (Editorial) 1069
Marinaro, A. T.
Pollution Abatement—The Masters' Electro-Plating Association and the National Association of Metal Finishers 1230
Marti, J. L.
Effect of Some Variables upon Internal Stress of Nickel as Deposited from Sulfamate Electrolytes 61
Metallic Impurities in Nickel Plating Solutions, G. J. Greenall and C. M. Whittington 217
Mickelson, F. L.
Problems in Finishing Aluminum Castings 1319
Miller, G. A.
Rapid Gravimetric Determination of Gold in Plating Baths 100
Mogerman, W. D.
Computers and Plating 1351
Molds and Dies, Electroformed, P. Baeyens 591
Mondolfo, L. F. and D. W. Levinson
Electroplating on Aluminum Alloys 986
Morico, J. L. and E. B. Saubestre
Dilute Zincating Solutions for Plating on Aluminum 899
Morrison, J. R., J. S. Judge, and D. E. Speliotis
Flexible Recording Surfaces of Electrodeposited Cobalt-Nickel-Phosphorus 441
Murphy, T. P.
Keynote Address, Second Airline Plating Forum 705

N

NAMF-AES Trade Tour to the Orient, Report on the, A. W. Logozzo and E. E. Oberland 694
Nechaev, E. A., N. T. Kudryavtsev, and R. U. Beck
Electrodeposition of Silver from Cyanide Solutions at a High Current Density 889
Nelson, G. D.
Quality and Cost Improvement in the Aluminum Bright Anodizing Process. IV. Trouble-Shooting the Process 610
Nelson, G. D., C. P. Schumacher, W. J. Shortreed and J. T. Sommerfeld
Quality and Cost Improvement in the Aluminum Bright Anodizing Process III. The Recovery of Phosphoric Acid from Aluminum Bright Dip Rinse Solution 72
Nelson, G. D. and F. B. Clarke
Analysis of Phosphoric-Sulfuric Mild Steel Etching Baths 474
New Developments in the Surface Science of Electric Contacts, M. Antler 1431

NICKEL

Nickel Anodes, The Effect of Sulfur, Phosphorus and Silicon Additives on the Activity and Types of Corrosion of Nickel Anodes, G. A. DiBari 1440
Nickel as Deposited from Sulfamate Electrolytes, Effect of Some Variables upon Internal Stress of, J. L. Marti 61
Nickel Coatings, High-Speed Plating of Industrial, F. X. Carlin ... 1203
Nickel, Corrosion Path in Bright, W. R. Doty 1099
Nickel from Leveling Solutions, Influence of Periodic Interruptions of Current on the Electrodeposition of, S. S. Kruglikov, N. T. Kudryavtsev, R. P. Sobolev, and A. Y. Antonov 78
Nickel-Chromium Plating System, Accelerated Electrolytic Corrosion Test and a Corrosion Analysis Procedure for the, Part I., R. L. Saur and R. P. Basco 35
Nickel-Cobalt Alloy, Electrodeposition of: Operating Variables and Physical Properties of the Deposits, D. W. Endicott and J. R. Knapp Jr. 43
Nickel Deposition, Initial Stages of, I. The Watts Bath, M. H. Jones and M. G. Kenez 995
Nickel Plating Solutions, Metallic Impurities in, G. J. Greenall and C. M. Whittington 217
Nickel Sulfamate Bath, Effect of Bromide Ion on Stress in a, H. Searles 204
Nickel Systems, Correlation of "EC" and CASS Tests to Service Using Duplex, R. L. Saur and R. P. Basco 320
Nickel Systems in Service and in the EC and CASS Tests, Corrosion of Triplex, R. L. Saur and R. P. Basco 981
Nickel, Tarnishing of Thin Rhenium Deposits on: Effect of Plating Process Anions and Ultrasonics, E. K. Camp 318
Nobel, F. I., B. D. Ostrow, R. B. Kessler, and D. W. Thomson
Factors That Influence Gold Metal Distribution in Barrel Plating ... 1099
Nominating Committee, E. E. Oberland, (Editorial) 155
Noonan, H. J.
Electrographic Determination of Porosity in Gold Electrodeposits. 461

O

Oberland, E. E.
Nominating Committee (Editorial). 155

Oberland, E. E. and A. W. Logozzo
Report on the NAMF-AES Trade Tour to the Orient 694

OBITUARIES

Blum, Mrs. W. 837
Burgess, G. 1495
Coady, P. M. 1161
Field, S. 389
Hoffheimer, A. Sr. 526
Kelly, C. 653
Miller, R. P. 1495
Nyquist, R. L. 1365
Puma, F. 21
Ribbe, A. P. 1495
Sexton, J. P. 652
Siegel, H. J. 1495
Smallman, H. R. 653
Smith, F. K. 264
Wiarda, Mrs. W. M. 1365
Ziegfeld, R. L. 389

Oil, Rustproofing with Phosphate and, R. E. Stephenson and A. E. Weber 39
Olivero, A. and E. Villata
Sodium Cyanide Determination in Cyanide Zinc Plating Solutions .. 770
Ostrow, B. D., F. I. Nobel, R. B. Kessler and D. W. Thomson
Factors That Influence Gold Metal Distribution in Barrel Plating ... 1099

P

Paint Adhesion to Decorative Trim, W. S. Garwood 1323
Paint, Electrodeposition of, E. F. Alford 478
Parisho, G. E.
What Is Public Relations? (Editorial) 957
Parthasaradhy, P. Jayakrishnan, and S. R. Rajagopalan
Some Experiences in Copper Electroforming of Wave Guides 1453
Peace on Earth, G. W. Cavanaugh (Editorial) 1407
Pech, W.
Program-Controlled Fully Automatic Machines for Electroplating 193
Peptone in Solder Baths, Determination of; Determination of Certain Additives in Plating Baths, G. W. Dollman 1448
Persulfate from Printed Circuit Etchants, Recovery of, K. J. Radimer, F. E. Caropreso, D. Goldstein, G. W. Siwinski, and B. J. Hogya .. 1445
Pesetsky, B., J. E. Knap and F. N. Hill
Vapor Plating with Dicumenechromium: Preparation and Properties of the Chromium Plate ... 772
Pfeiffer, W., A. Knoedler, and E. Raub
Gold Electrodeposits from Cyanoaurate (III) Solutions and Some Characteristics of the Cyanoaurate Complex 765
Philosophy of Work, A. G. Gray (Editorial) 1175
Phosphate and Oil, Rustproofing with, R. E. Stephenson and A. E. Weber 39
Phosphoric Acid from Aluminum Bright Dip Rinse Solution, the Recovery of. (III), Quality and Cost Improvement in the Aluminum Bright Anodizing Process, G. D. Nelson, C. P. Schumacher, W. J. Shortreed, and J. T. Sommerfeld 72
Phosphoric-Sulfuric Mild Steel Etching Baths, Analysis of, G. D. Nelson and F. B. Clarke 474
Phosphorous, and Silicon Additives on the Activity and Type of Corrosion of Nickel Anodes, The Effect of Sulfur, G. A. DiBari 1440
Physical and Mechanical Properties of Electrodeposited Metals, N. P. Fedot'ev 309
Pinkerton, H. L., and A. K. Graham
Dollars and Sense about Plating Waste Treatment and Water Conservation 1222
Plastics, Plating on, C. C. Weekly ... 107
Plating Electrochemist's First Trip Abroad, G. Dubpernell 702
Plating on Plastics, C. C. Weekly 107
Plating Problems Forum, "I'd Like to Know" 326

PLATING TOPICS

Airless Spray Painting, J. H. Reichenbach 991
Colorimetric Control Procedures for Proprietary Gold Plating Solutions, P. C. Baldwin 1450
Electrodeposition of Paint, E. F. Alford 478
Plating on Plastics, C. C. Weekly .. 107
Pollution Abatement—The Masters' Electro-Plating Association and the National Association of Metal Finishers, A. T. Marinaro 1230
Saturn V Guidance System Protective Finish, L. P. Cabrinety and R. A. Hagstrom 331
Some Experiences in Copper Electroforming of Wave Guides, P. Jayakrishnan, N. V. Parthasaradhy, and S. R. Rajagopalan ... 1453
Some Production Plating Problems and How They Were Solved, Part III, S. Heiman 110
Some Production Plating Problems and How They Were Solved, Part IV, S. Heiman 333
Some Production Plating Problems and How They Were Solved, Part V, S. Heiman 615
Some Production Plating Problems and How They Were Solved, Part VI, S. J. Beyer and S. Heiman 905
Some Production Plating Problems and How They Were Solved, Part VII, S. Heiman 1122
Some Production Plating Problems and How They Were Solved, Part VIII, S. Heiman 1343
Wire Plating, D. Elliott 335
Pollution Abatement—The Masters' Electro-Plating Association and the National Association of Metal Finishers 1230

POROSITY

Porosity in Gold Electrodeposits, Electrographic Determination of, H. J. Noonan 461
Porosity of Gold Electrodeposits by Quantitative Electrography, Determination of the, S. M. Garte .. 1331
Porosity of Gold Electrodeposits, Effect of Substrate Roughness on the, S. M. Garte 1335
Porosity Testing of Electroplated Gold in Gelled Media, F. V. Bedetti and R. V. Chiarenzelli .. 305
Predicting Current Distribution on a Cathode: "Plating Simulation" vs Mathematics, J. J. Christie 1207
Printed Circuits, Effect of Board Thickness to Hole Diameter Ratio on Plating of, B. F. Rothschild ... 437
Printed Circuit Etchants, Recovery of Persulfate from, K. J. Radimer, F. E. Caropreso, D. Goldstein, G. W. Siwinski, and B. J. Hogya .. 1445
Printed Circuits, Stepwise Countercurrent Etching of, K. J. Radimer, D. A. Lloyd, and B. J. Hogya 598
Problems in Finishing Aluminum Castings, F. L. Mickelson 1319
Program-Controlled Fully Automatic Machines for Electroplating, W. Pech 193
Properties of Electroformed Aluminum, F. J. Schmidt and I. J. Hess .. 229

Q

Quality and Cost Improvement in the Aluminum Bright Anodizing Process III. The Recovery of Phosphoric Acid from Aluminum Bright Dip Rinse Solution, G. D. Nelson, C. P. Schumacher, W. J. Shortreed, and J. T. Sommerfeld 72
Quality and Cost Improvement in the Aluminum Bright Anodizing Process IV. Trouble-Shooting the Process, G. D. Nelson 610

R

Radimer, K. J., D. A. Lloyd and B. J. Hogya
Stepwise Countercurrent Etching of Printed Circuits 598
Radimer, K. J., F. E. Caropreso, D. Goldstein, G. W. Siwinski, and B. J. Hogya
Recovery of Persulfate from Printed Circuit Etchants 1445
Rapid Gravimetric Determination of Gold in Plating Baths, G. A. Miller 100
Rapid Spectrophotometric Determination of Copper in Ferric Chloride Etching Baths, F. J. Conrad and B. T. Kenna 763
Rajagopalan, P. Jayakrishnan and N. V. Parthasaradhy
Some Experiences in Copper Electroforming of Wave Guides 1453
Raub, E., A. Knoedler, and W. Pfeiffer
Gold Electrodeposits from Cyanoaurate (III) Solutions and Some Characteristics of the Cyanoaurate Complex 765
Reaching New Horizons, G. W. Cavanaugh (Editorial) 853
Recording Surfaces of Electrodeposited Cobalt-Nickel-Phosphorus, Flexible, J. S. Judge, J. R. Morrison, and D. E. Speliotis 441
Recovery of Persulfate from Printed Circuit Etchants, J. J. Radimer, F. E. Caropreso, D. Goldstein, G. W. Siwinski and B. J. Hogya .. 1445
Regulations for Industrial Waste in State of Connecticut, J. J. Curry .. 659
Reichenbach, J. H.
Airless Spray Painting 991
Repressing the Growth of Tin Whiskers, S. M. Arnold 96
Rhenium Deposits on Nickel, Tarnishing of: Effect of Plating Process Anions and Ultrasonics, E. K. Camp 318
Ribicoff, A. A.
Federal Aspects of Industrial Waste Disposal 657
Rogers, R. R., W. Dingley and J. Bednar
Stable Copper Cyanide Plating Baths 602
Rotary Cathode Plating Test Cell, Examination of Barrel Plating Solutions Through the Use of the, E. G. Chapdelaine 471
Rothschild, B. F.
Effect of Board Thickness to Hole Diameter Ratio on Plating of Printed Circuits 437
Rustproofing with Phosphate and Oil, R. E. Stephenson and A. E. Weber 39

S

Safranek, W. H.
AES Expands and Diversifies Its Publication Features (Editorial). 1291
A Survey of Electroforming for Fabricating Structures. 1211
Saturn V Guidance System Protective Finish, L. P. Cabrinety and R. A. Hagstrom. 331
Saubestre, E. B. and J. L. Morico
Dilute Zincating Solutions for Plating on Aluminum. 899
Saur, R. L.
Calculation of the Maximum Current Density for Corroding Specimens in the EC Test. 1124
Saur, R. L. and R. P. Basco
Accelerated Electrolytic Corrosion Test and a Corrosion Analysis Procedure for the Nickel-Chromium Plating System, Part I. 35
Correlation of "EC" and CASS Tests to Service Using Duplex Nickel Systems. 320
Corrosion of Triplex Nickel Systems in Service and in the EC and CASS Tests. 981
Schmidt, F. J. and I. J. Hess
Properties of Electroformed Aluminum. 229
Schumacher, B. W.
Use of the Electron Beam Thickness Gage on Multi-Layered Coatings 1235
Schumacher, C. P., W. J. Shortreed, J. T. Sommerfeld, and G. D. Nelson
Quality and Cost Improvement in the Aluminum Bright Anodizing Process. III. The Recovery of Phosphoric Acid from Aluminum Bright Dip Rinse Solution. 72
Scope, L. L. Diveley (Editorial). 733
Sealing of Chromic Acid Anodized Aluminum, H. Geduld. 1002
Searles, H.
Effect of Bromide Ion on Stress in a Nickel Sulfamate Bath. 204
Shortreed, W. J., J. T. Sommerfeld, G. D. Nelson and C. P. Schumacher
Quality and Cost Improvement in the Aluminum Bright Anodizing Process. III. The Recovery of Phosphoric Acid from Aluminum Bright Dip Rinse Solution. 72
Silicates as Cleaners in the Production of Tinplate, L. J. Brown. 225
Silicon Additives on the Activity and Type of Corrosion of Nickel Anodes, The Effect of Sulfur, Phosphorus and, G. A. DiBari. 1440
Silver Electrodeposits, Hardness and Abrasion Resistance of Bright, R. Weiner. 894
Silver from Cyanide Solutions at a High Current Density, Electrodeposition of, N. T. Kudryavtsev, R. U. Beck and E. A. Nechaev. 889
Siwinski, G. W., K. J. Radimer, F. E. Caropreso, D. Goldstein, and B. J. Hogya
Recovery of Persulfate from Printed Circuit Etchants. 1445
Sobolev, R. P., A. Y. Antonov, S. S. Kruglikov, and N. T. Kudryavtsev
Influence of Periodic Interruptions of Current on the Electrodeposition of Nickel from Leveling Solutions. 78
Soderberg, K. G.
A Glamorous Time—A Look Back 1262
Sodium Cyanide Determination in Cyanide Zinc Plating Solutions, A. Olivero and E. Villata. 770
Solderability of Lead Wires, A System for Numerical Evaluation of the, W. H. Wade and G. W. Brown. 783
Solder Baths, Determination of Peptone in; Determination of Certain Additives in Plating Baths, G. W. Dollman. 1448
Some Aspects of Plating Research in Japan—Visits to a Few University Laboratories, S. Heiman and A. Catchmark. 828
Some Experiences in Copper Electroforming of Wave Guides, P. Jayakrishnan, N. V. Parthasaradhy, and S. R. Rajagopalan. 1453
Some Production Plating Problems and How They Were Solved, S. Heiman, Part III. 110
Some Production Plating Problems and How They Were Solved, S. Heiman, Part IV. 333
Some Production Plating Problems and How They Were Solved, S. Heiman, Part V. 615
Some Production Plating Problems and How They Were Solved, Part VI, S. J. Beyer and S. Heiman 905
Some Production Plating Problems and How They Were Solved, S. Heiman, Part VII. 1122
Some Production Plating Problems and How They Were Solved, S. Heiman, Part VIII. 1343
Sommerfeld, J. T., G. D. Nelson, C. P. Schumacher, and W. J. Shortreed
Quality and Cost Improvement in the Aluminum Bright Anodizing Process. III. The Recovery of Phosphoric Acid from Aluminum Bright Dip Rinse Solution. 72
Speliotis, D. E., J. S. Judge and J. R. Morrison
Flexible Recording Surfaces of Electrodeposited Cobalt-Nickel-Phosphorus. 441
Spooner, R. C.
Chemical Composition of Sulfuric Acid Anodic Films on Aluminum Alloys. 451
Spray Painting, Airless, J. H. Reichenbach. 991
Stable Copper Cyanide Plating Baths, W. Dingley, J. Bednar, and R. R. Rogers. 602
Stearic Acid Films on the Overpotential for Hydrogen Evolution, The Effect of, (Part XVII, Cleaning and Preparation of Metals Prior to Electroplating), M. A. Farrell and H. B. Linford. 1110
Steel, Influence of Etch Bath on the Adhesion of Chromium Deposited on, W. H. Dancy and A. Zavarella 618
Stephenson, R. E. and A. E. Weber
Rustproofing with Phosphate and Oil. 39
Stephenson, W. B. Jr.
Development and Utilization of a High Strength Alloy for Electroforming. 183
Stone, J., H. A. Tuttle and H. N. Bogart
Ford Anodized Aluminum Corrosion Test—FACT. 877
Stepwise Countercurrent Etching of Printed Circuits, K. J. Radimer, D. A. Lloyd, and B. J. Hogya. 598
Stress in a Nickel Sulfamate Bath, Effect of Bromide Ion on, H. Searles. 204
Such, J. E., United Kingdom. 235, 1455
Sulfate Bath, The, (II) Physical and Mechanical Properties of Electrodeposited Copper, AES Research Project No. 21, V. A. Lamb and D. R. Valentine. 86
Sulfuric Acid Anodic Films on Aluminum Alloys, Chemical Composition of, R. C. Spooner. 451
Sulfur, Phosphorus and Silicon Additives on the Activity and Type of Corrosion of Nickel Anodes, G. A. DiBari. 1440
Survey of Electroforming for Fabricating Structures, W. H. Safranek. 1211
Swalheim, D. A.
Training (Editorial). 403
System for Numerical Evaluation of the Solderability of Lead Wires, W. H. Wade and G. W. Brown. 783

T

Tarnishing of Thin Rhenium Deposits on Nickel: Effect of Plating Process Anions and Ultrasonics, E. K. Camp. 318

TECHNICAL BRIEFS

Calculation of the Maximum Current Density for Corroding Specimens in the EC Test, R. L. Saur 1124
Improving Adhesion of Plated Coatings on Selected Areas of Aluminum Alloys, M. Ben and W. D. Brooks. 480
Influence of Etch Bath on the Adhesion of Chromium Deposited on Steel, W. H. Dancy Jr., and A. Zavarella. 618
Technique for Electroplating Glass Fiber Teflon Laminate, C. E. Whitfield. 1008
Use of the Electron Beam Thickness Gage on Multi-Layered Coatings, B. W. Schumacher. 1235
Technique for Electroplating Glass Fiber Teflon Laminate, C. E. Whitfield. 1008
Teflon Laminate, Technique for Electroplating Glass Fiber, C. W. Whitfield. 1008
Thomson, D. W., F. I. Nobel, B. D. Ostrow, and R. B. Kessler
Factors That Influence Gold Metal Distribution in Barrel Plating. 1099
Tinplate, Silicates as Cleaners in the Production of, L. J. Brown. 225
Tin Whiskers, Repressing the Growth of, S. M. Arnold. 96
Training, D. A. Swalheim (Editorial) 403
Trouble-Shooting the Process, IV, Quality and Cost Improvement in the Aluminum Bright Anodizing Process, G. D. Nelson. 610
Turner, D. R.
Changing Nature of AES-Sponsored Research (Editorial). 283
Tuttle, H. A., J. Stone and H. N. Bogart
Ford Anodized Aluminum Corrosion Test—FACT. 877

U

Ultrasonics, Effect of Plating Process Anions and (Tarnishing of Thin Rhenium Deposits on Nickel), E. K. Camp. 318
Use of the Electron Beam Thickness Gage on Multi-Layered Coatings, B. W. Schumacher. 1235

V

Vacuum Metalizers through Simple Maintenance, Improved Productivity of, H. B. Hebble Jr. 1048
Valentine, D. R. and V. A. Lamb
AES Research Project No. 21—Physical and Mechanical Properties of Electrodeposited Copper II. The Sulfate Bath. 86
Vapor Plating with Dicumenechromium: Preparation and Properties

of the Chromium Plate, J. E. Knap, B. Pesetsky and F. N. Hill 772
Villata, E. and A. Olivero
Sodium Cyanide Determination in Cyanide Zinc Plating Solutions .. 770

W

Wade, W. H. and G. W. Brown
System for Numerical Evaluation of the Solderability of Lead Wires 783
Walton, R. F.
Effect of Type and Porosity of Gold Deposits on the Contact Resistance of Electroplated Materials .. 209
Wastes, Disposal and Recovery of Electroplating, G. E. Barnes 1115
Wastes for 1965, Bibliography of Metal Finishing, D. G. Foulke 1459
Waste Treatment and the Metal Finishing Industry, D. G. Foulke .. 1217
Waste Treatment and Water Conservation, Dollars and Sense about Plating, A. K. Graham and H. L. Pinkerton 1222
Water Conservation, Dollars and Sense about Plating Waste Treatment and, A. K. Graham and H. L. Pinkerton 1222
Watts Bath, I., Initial Stages of Nickel Deposition, M. H. Jones and M. G. Kenez 995
Weber, A. E. and R. E. Stephenson
Rustproofing with Phosphate and Oil 39
Weekly, C. C.
Plating on Plastics 107
Weil, R. and W. N. Jacobus Jr.
About Two Microstructural Features of Electrodeposits 102
Weiner, R.
Hardness and Abrasion Resistance of Bright Silver Electrodeposits .. 894
What Is Public Relations? G. E. Parisho (Editorial) 957
Whitfield, C. E.
Technique for Electroplating Glass Fiber Teflon Laminate 1008
Whittington, C. M. and G. J. Greenall
Metallic Impurities in Nickel Plating Solutions 217
Wire Plating, D. Elliott 335

Z

Zavarella, A. and W. H. Dancy Jr.
Influence of Etch Bath on the Adhesion of Chromium Deposited on Steel 618
Zincating Solutions for Plating on Aluminum, Dilute, E. B. Saubestre and J. L. Morico 899

PATENT ABSTRACTS

A

ALLOYS

Alloy Plating of Reed Switches—3,251,121, 5/17/66—K. B. Prival 1258
Electroless Nickel-Iron Alloy—3,255,033, 6/7/66—A. F. Schneckenbecher 1384
Nickel-Phosphorous Alloy—3,236,752, 2/22/66—D. E. Couch 932

ALUMINUM

Aluminum Coating—3,220,876, 11/30/65—R. Moeller 708
Aluminum Deposition—3,259,557, 7/5/66—E. J. Smith 1486
Aluminum Plating—3,214,288, 10/26/65—L. McGraw 511
Aluminum Plating from Molten Bath—3,236,751, 2/22/66—K. Azuma 932
Coloring Anodized Aluminum—3,218,243, 11/16/65—C. Michelson 512
Electropolishing Aluminum—3,232,855, 2/1/66—Y. Shibasaki 819
Etching Aluminum—3,249,523, 5/3/66—W. Post and E. Worschischek 1257
Method of Anodizing Aluminum—3,243,362, 3/29/66—J. H. Manhart 1053
Silver Coating Aluminum—3,251,128, 5/17/66—J. M. Ohno 1258
Water Soluble Basic Aluminum—3,240,687, 3/15/66—J. Konig and H. K. Platzer 934

ANODIZING

Anode—3,236,756, 2/22/66—H. B. Beer 932
Anodizing—3,240,685, 3/15/66—L. I. Maissel 934
Anodizing Aluminum—3,227,639, 1/4/66—W. P. Kampert 710
Anodizing—3,252,875, 5/24/66—G. Economy 1383
Anodizing—3,254,014, 5/31/66—J. S. Daddona 1384
Anodizing Treatment—3,216,866, 11/9/65—J. Orlin 512

B

BONDING

Bonding of Stainless Steel to Aluminum—3,242,565, 3/29/66—R. E. North and D. A. Domrose 1050
Contacts—3,209,450, 10/5/65—E. Klein and R. MacDonald 240
Method of Bonding Coatings—3,227,636, 1/4/66—H. G. DeHart 710

C

CHROMIUM

Chromium-Plated Metal Structures—3,249,409, 5/3/66—H. G. McLeod 1257
Chromium Plating—3,203,876, 8/31/65—A. Deyrup 18
Chromium Plating—3,205,153, 9/7/65—S. Casper 18
Chromium Plating—3,232,854, 2/1/66—W. O. MacLean 819
Chromium Plating—3,247,083, 4/19/66—L. W. Raymond and R. E. Heath 1256
Chromizing—3,222,212, 12/7/65—G. Samuel 709
High-Purity Chromium—3,259,560, 7/5/66—E. A. Brandes and J. A. Whittaker 1486
Plating Bright Chromium—3,248,310, 4/26/66—G. R. Schaer 1256

CIRCUITS

Circuit Boards—3,208,921, 9/28/65—C. Hill 239
Circuit Method—3,210,214, 10/5/65—B. Smith 240
Circuit Production—3,256,588, 6/21/66—T. V. Sukima and F. L. Murray Jr. 1485

CLEANING

Aluminum Cleaner—3,210,287, 10/5/65—D. Kelly and H. Wissman 240
Carbon Remover—3,216,857, 11/9/65—J. Duvall 512
Cleaner—3,207,683, 9/21/65—G. Hermann 239
Cleaner—3,218,260, 11/16/65—T. Lewandowski 521
Cleaning—3,246,659, 4/19/66—T. B. Ballard 1158
Cleaning Composition—3,255,118, 6/7/66—J. W. Carroll and H. V. Smith 1485
Cleaning Semiconductors—3,224,904, 12/21/65—D. Klein 710
Detergent—3,223,646, 12/14/65—J. McKenna 709
Electroless Nickel Stripper—3,203,787, 8/31/65—J. Grunwald 18
Oxide Removal—3,242,093, 3/22/66—W. A. Compton 1050
Scale Removal—3,248,269, 4/26/66—W. E. Bell 1256
Stabilized Solvents—3,238,137, 3/1/66—G. N. Grammer and P. W. Trotter 933
Ultrasonic Cleaning—3,222,221, 12/7/65—N. Branson 709
Ultrasonic Transducer—3,210,052, 10/5/65—A. Gaal 240

COATINGS

Automatic Uniform Coatings—3,251,710, 5/17/66—H. J. Taylor and R. L. Winn 1383
Boride Coating—3,251,179, 5/17/66—F. Tepper 1383
Chromide Coating—3,232,853, 2/1/66—N. C. Cook 818
Coating Columbium—3,219,474, 11/23/65—S. Priceman 521
Coating Molybdenum—3,241,949, 3/22/66—W. Kunda 1050
Coating with Aluminum—3,227,577, 1/4/66—K. H. Baesler 710
Conductive Coating—3,249,559, 5/3/66—W. Gallas 1258
Conversion Coating—3,232,594, 2/1/66—R. Ord Jr. 818
Corrosion-Resistant Ferrous Coating—3,249,524, 5/3/66—D. B. Sheldahl 1257
Diffusion Coating—3,249,456, 5/3/66—M. C. Carosella 1257
Electrophoresis—3,254,004, 5/31/66—T. Jackson and A. McPherson 1384
Electrophoretically Deposited Coating—3,259,562, 7/5/66—F. W. Salt and K. G. Lewis 1486
Ferrate Coating—3,206,384, 9/14/65—P. Margulies and W. Tillis .. 18
Finishing Stainless Steel—3,208,874, 9/28/65—J. Conner 239
Immersion Wire Coating—3,238,059, 3/1/66—M. J. Stobierski ... 932
Insulating Steel—3,207,636, 9/21/65—T. Wada 239
Magnesium Hydroxide Coating—3,208,922, 9/28/65—J. McQuade 240
Metal Coating—3,222,218, 12/7/65—M. Beltzer 709
Method of Depositing a Metallic Oxide—3,243,363, 3/29/66—G. H. W. Helwig 1053
Plating on Aluminum—3,235,404, 2/15/66—F. Mickelson and R. E. Pettit 819
Protective Coating—3,254,005, 3/5/66—F. J. Kennedy 1384
Stainless Steel Coating—3,210,220, 10/5/65—N. Clegg and W. Greening 240
Tin Oxide Coating—3,255,035, 6/7/66—P. J. Clough 1485

COPPER

Copper Plating—3,216,913, 11/9/65—A. Debe 512
Cyanide Copper Plating—3,219,560, 11/23/65—P. Leenders 521
Electroless Copper—3,222,195, 12/7/65—F. Pearlstein 708
Electroless Copper—3,222,207, 12/7/65—J. Marshall 709

Electroless Copper—3,246,994, 4/19/66—I. M. Ritchie 1158
Electroless Copper—3,257,215, 6/21/66—F. W. Schneble Jr. 1485
Electroless Copper Sensitizing—3,259,559, 7/5/66—F. W. Schneble Jr. 1486

CORROSION RESISTANCE

Antitarnish for Copper—3,248,235, 4/26/66—D. M. Pyor and L. F. Cason 1256
Coating for Corrosion Resistance—3,249,447, 5/3/66—W. A. Higgins 1257
Corrosion-Inhibited Phosphate Solutions—3,257,316, 6/21/66—R. P. Langguth and W. Morgenthaler 1486
Corrosion Inhibitor—3,240,707, 3,240,708—3/15/66—J. Dulat 934
Corrosion Inhibitor—3,240,714, 3/15/66—C. Rai 1050
Corrosion Inhibitor—3,243,379, 3/29/66—E. E. Clayton Jr. 1053
Corrosion Inhibitor—3,248,334, 4/26/66—R. F. Monroe 1256
Corrosion Inhibitor—3,249,547, 5/3/66—A. O. Fisher 1258
Corrosion Inhibitor—3,249,548, 5/3/66—C. O. Herman 1258
Corrosion Inhibitor—3,250,706, 5/10/66—W. E. Kuhn and C. C. Nathan 1258
Corrosion Inhibitor—3,255,121, 6/7/66—D. L. Rizzo Jr. 1485
Corrosion Inhibitor—3,257,244, 6/21/66—E. F. Barkman 1485
Corrosion Proofing Composition—3,241,983, 3/22/66—J. Betz 1050
Corrosion-Resistant Coating—3,247,028, 4/19/66—H. G. Klein and E. Zingieble 1256
Plating for Corrosion Resistance—3,247,082, 4/19/66 1256

D

DEPOSITION

Deposition from Alkoxides—3,216,845, 11/9/65—J. Brown 512
Deposition of Magnetic Alloy Films—3,239,437, 3/8/66—J. H. Stephen 933
Electroless Deposition—3,238,061, 3/1/66—H. Koretzky and B. Leland 932
Liquid Cathode—3,208,920, 9/28/65—R. Crew 239

E

ELECTROCHEMICAL MACHINING

Electrochemical Machining—3,219,564, 11/23/65—B. Wilkinson 521
Electrochemical Machining—3,224,953, 12/21/65—J. Russell 710
Electrochemical Machining—3,228,863, 1/11/66—G. E. Wanttaja and J. Haupt 817
Electrochemical Machining—3,230,160, 1/18/66—G. C. Kennedy ... 817
Electrolytic Machining—3,256,165, 6/14/66—L. A. Williams 1485
Electrolytic Machining—3,257,300, 6/21/66—L. A. Williams 1486
Electrolytic Machining—3,257,306, 6/21/66—R. S. Webb 1486
Electromachining—3,242,062, 3/22/66—L. C. Covington 1050
Machining—3,247,087, 4/19/66—L. Gauthier 1256

ELECTROLESS PLATING

Electroless Plating—3,212,917, 10/19/65—I. Tsu and R. Smith 377
Electroless Plating—3,242,361, 3/29/66—R. V. Clark 1053

ELECTROPLATING

Electroplating Method of Producing an Active Anode—3,236,750, 2/22/66—H. D. Hughes 932
Plating—3,238,112, 3/1/66—J. H. Haslam 933
Plating—3,228,861, 1/11/66—A. Vogt and P. E. Beyeler 817
Plating—3,249,520, 5/3/66—G. Hermann 1257
Plating—3,251,712, 5/17/66—C. Berger 1383
Plating on Molybdenum and Tungsten—3,239,439, 3/8/66—G. H. Helmke 934
Ribbon Electroplating Method—3,259,556, 7/5/66 1486
Self-Regulating Acid Plating Process—3,257,294, 6/21/66—G. M. Dusseldorf 1486

EQUIPMENT

Anode Basket—3,223,611, 12/14/65—K. Wells 709
Anode Shifting Device—3,256,171, 6/14/66—A. F. Gualdieri Sr. and M. A. Plantin 1485
Apparatus for Electroless Nickel Coating—3,247,013, 4/19/66—J. R. Spraul and D. E. Metheny ... 1256
Automatic Plating—3,208,600, 9/28/65—A. Bignall and L. Kumpf 239
Automatic Stripline—3,226,315, 12/28/65—E. Smith 710
Barrel—3,205,159, 9/7/65—E. Neilson 18
Buffing Wheel—3,208,893, 9/28/65 G. Churchill 239
Cathode Sputtering—3,250,694, 5/10/66—L. I. Maissel and J. Riseman 1258
Conversion Coating—3,215,564, 11/2/65—J. Thirsk 511
Conveyor—3,243,032, 3/29/66—L. J. Chambon 1053
Conveyor—3,252,603, 5/24/66—J. V. Davis 1383
Conveyor Apparatus—3,250,369, 5/10/66—L. J. Pianowski and G. J. Latona 1258
Conveyor System—3,220,534, 11/30/65—H. Abbey 708
Deburring—3,246,429, 4/19/66—P. P. Ruppe 1158
Electrochemical Machinery—3,208,923, 9/28/65—M. Feiner 240
Electrode—3,257,717, 6/28/66—B. W. Wilkinson and S. J. Thornliebank 1486
Electrolytic Cell—3,257,307, 6/21/66—J. L. Henry and R. D. Holliday 1486
Electro Machining—3,252,881, 5/24/66—K. Inone 1383
Etchant—3,216,873, 11/9/65—R. Jones 512
Etcher—3,210,263, 10/5/65—W. Jones 240
Etching Apparatus—3,224,914, 12/21/65—R. Benton 710
Galvanizing—3,256,592, 6/21/66—T. H. Krengel and E. Wilk 1485
Manufacture of Semiconductor—3,253,320, 5/31/66—P. R. Levi-Lamond 1384
Metalizing—3,249,087, 5/3/66—G. P. McGraw Jr. 1257
Nickel Electrode—3,211,587, 10/12/65—R. Shair and H. Seiger 240
Plating Apparatus—3,223,600, 12/14/65—B. Andersson 709
Plating Apparatus—3,226,308, 12/28/65—H. Pochapsky 710
Plating Barrel—3,265,170, 6/14/66—E. O. Neilson 1485
Plating Fixture—3,223,599, 12/14/65—D. Taylor 709
Plating Rack—3,257,308, 6/21/66—J. C. Colton 1486
Plating Rack—3,259,563, 7/5/66—P. P. Del Monica 1486
Producing a Capacitor—3,258,826, 7/5/66—S. Boone and H. Voeten 1486
Rack for Plating of Rollers—3,244,613, 4/5/66—F. B. Karlquist 1053
Sand Blasting—3,256,642, 6/21/66—R. R. Ponti 1485
Self-Regulating Plating Baths—3,245,886, 4/12/66—G. Michael .. 1158
Slip-Ring Assembly—3,242,866, 4/5/66—J. J. Pandapas 1053
Sludge Control—3,252,882, 5/24/66—L. A. Williams 1384
Uniform Coating—3,251,339, 5/17/66—M. G. Whitfield 1258
Vibratory Finishing—3,209,497, 10/5/65—G. Powell 240

ETCHING

Chemical Etching of Tungsten—3,323,803, 2/1/66—G. D. Barnett and A. Mitchell Jr. 818
Etching Bath—3,251,777, 5/17/66—J. A. Easley 1383
Etching Composition—3,253,968, 5/31/66—C. C. Shepard Jr. and J. Derbyshire Jr. 1384
Etching Rhodium—3,240,684, 3/15/66—R. L. Martin and C. J. Williams 934

G

GALVANIZING

Galvanizing—3,206,324, 9/14/65—J. Daesen 18
Galvanizing—3,244,551, 4/5/66—S. M. Heins 1053

GOLD

Electroless Gold—3,214,292, 10/26/65—G. Edson 511
Gold Decorating Compositions—3,245,809, 4/12/66—H. M. Fitch 1157
Gold Plating—Re: 25,883, 10/19/65—R. Duva and D. Foulke 377
Gold Stripper—3,242,090, 3/22/66—J. J. Grunwald 1050

I

IMMERSION PLATING

Immersion Plating—3,230,098, 1/18/66—R. W. Robinson 817
Immersion Plating—3,231,396, 1/25/66—H. K. Delong 818

M

METALIZING

Metalizing—3,215,555, 11/2/65—R. Krey 511
Metalizing—3,251,341, 5/17/66—W. H. Eburn Jr. and J. A. Hamilton 1258

MISCELLANEOUS

Abrasive—3,211,634, 10/12/65—M. Lorenzo 240
Blackening—3,219,489, 11/23/65—K. Bellinger 521
Brightener for Cyanide Plating Baths—3,227,638, 1/4/66—R. H. Burnson and L. Rucius 710
Chemical Treatment—3,257,295, 6/21/66—S. Yonezaki 1486
Corrosion Measurement—3,250,689, 5/10/66—R. G. Seyl 1258
Electrochemical Product—3,230,718, 2/1/66—E. J. Seyb and A. J. Wallace 818
Electrode—3,234,110, 2/8/66—H. B. Beer 819

Electroless Nickel and/or Cobalt—3,234,031, 2/8/66—E. Zirngiebel and H. G. Klein 819
Electrolytically Applied Insulative Material—3,257,304, 6/21/66—E. G. Johnson 1486
Electrolytic Regeneration—3,252,-879, 5/24/66—R. Sommer 1383
Electropolishing—3,213,008, 10/19/65—S. Valentin 377
Electropurification of Alkaline Solutions—3,244,605, 4/5/66—R. L. Hotchkiss 1053
Electrowinning—3,244,604, 4/5/66—I. M. Diller 1053
Finishing—3,233,372, 2/8/66—H. Kobayashi 819
Fused Salt Electroplating—3,257,-293, 6/21/66—M. Chemla 1485
Grain Refiner—3,215,611, 11/2/65—F. Pawlek 511
Iridium Plating—3,207,680, 9/21/65—E. MacNamara 239
Joining of Parts—3,249,470, 5/3/66—J. H. Naake 1257
Lead Cladding—3,244,553, 4/5/66—J. E. Knapp and N. F. Ritchey 1053
Magnetic Film—3,240,686, 3/15/66—H. E. Towner 934
Method of Joining Metal Parts—3,238,613, 3/8/66—M. A. M. Bakker 933
Mechanical Plating—3,251,711, 5/17/66—R. Pottberg and E. T. Clayton 1258
Metalizing Glass—3,249,467, 5/3/66—S. D. Stookey 1257
Method of Making Wear-Resistant Surfaces—3,247,080, 4/19/66—M. A. Blumefeld 1256
Phosphatizing—3,247,027, 4/19/66—L. Fullhart Jr. and D. A. Swalheim 1256
Pickling Stainless Steel—3,230,172, 1/18/66—E. F. Gasperinin 818
Roll for Plating Tanks—3,245,897, 4/12/66—R. F. Lane 1158
Stabilized Solvent Composition—3,257,326, 6/21/66—L. Fullhart Jr. and D. A. Swalheim 1486
Surface Treating Article—3,242,618, 3/29/66—P. Kosar 1053
Test Cell—3,215,609, 11/2/65—E. Chapdelaine 511
Tester for Adhesion—3,223,598, 12/14/65—G. Jacky 709

N

NICKEL

Bright Nickel Plating—3,245,887, 4/12/66—F. Passal and W. R. Doty 1157
Bright Nickel Plating—3,254,007, 5/31/66—O. Kardos 1384
Electroless Nickel—3,211,578, 10/12/65—G. Gutzeit 240
Etching of Nickel Base Alloys—3,232,802, 2/1/66—S. Young Jr. and D. C. Mitchel Jr. 818
Leveling Nickel—3,206,383, 9/14/65—M. Kappel 18
Leveling Nickel—3,219,559, 11/23/65—B. Ostrow 521
Nickel Brightener—3,218,244, 11/16/65—F. Passal 512
Nickel Plating—3,203,877, 8/31/65—L. Facquet 18
Nickel Plating—3,220,940, 11/30/65—H. Brown 708
Nickel Plating—3,222,268, 12/7/65—R. Clauss 709
Nickel Plating—3,255,096, 6/7/66—T. L. Powle 1485

NITRIDING

Nitriding—3,208,885, 9/28/65—I. Muller 239
Nitriding—3,232,795, 2/1/66—I. I. Bessen 818

P

PALLADIUM

Electroless Palladium—3,235,392, 2/15/66—J. J. Miles 819
Palladium Black—3,219,481, 11/23/65—S. Chodosh 521
Plating Palladium Silver—3,226,-309, 12/28/65—J. Oxley 710

PHOSPHATING

Phosphating—3,202,534, 8/24/65—E. Dutch 18
Phosphating—3,203,835, 8/31/65—W. Blum 18
Phosphating—3,220,890, 11/30/65—W. Vullo 708
Phosphating—3,228,806, 1/11/66—L. Fullhart Jr. 817
Phosphating—3,249,471, 5/33/66—W. A. Higgins 1257

PLATINUM

Plating on Platinum—3,213,004, 10/19/65—F. Schmidt 377
Platinum Bath—3,206,382, 9/14/65—L. Wilson and N. Hopkins. 18

POLISHING

Electrochemical Polishing—3,234,-111, 2/8/66—J. A. Siefnicks 819
Polishing Wheel—3,206,894, 9/21/65—P. Schaffner 18

PRINTED CIRCUITS

Printed Circuit Board Fabrication—3,239,373, 3/8/66—L. S. Hoodwin 933
Production of Printed Circuits—3,239,441, 3/8/66—S. L. Marosi .. 934

S

SILVER

Bright Silver—3,215,610, 11/2/65—W. Skaliks 511
Bright Silver—3,219,558, 11/23/65—D. G. Foulke 521

STEEL

Anodizing Stainless Steel—3,247,-086, 4/19/66—D. Goldstein and A. Moskowitz 1256
Bismuth Plating on Steel—3,256,-160, 6/14/66—J. A. McCarthy ... 1485
Galvanizing Steel—3,228,788, 1/11/66—A. Teplitz 817
Nickel-Plated Steel—3,245,885, 4/12/66—H. Asano and K. Segawa. 1157

STRIPPING

Metal Stripper—3,231,503, 1/25/66—E. Lave 818
Paint Stripper—3,216,945, 11/9/65—A. Mankowich 512
Stripper—3,257,299, 6/21/66—M. Mekjean 1486
Stripping—3,245,780, 4/12/66—M. Weisberg and F. P. Butler 1157

T

TIN

Acid Tin Plating—3,230,159, 1/18/66—S. O. Yonezaki 817
Tin Plate Treatment—3,216,912, 11/9/65—T. Shoemaker 512

TITANIUM

Pickling Titanium and Its Alloys—3,239,440, 3/8/66—L. C. Covington 933
Plating on Titanium—3,207,679, 9/21/65—F. Schmidt 239

V

VACUUM METALIZING

Vacuum Metalizing—3,205,086, 9/7/65—R. M. Brick and C. E. Maier 18
Vacuum Metalizing—3,205,087, 9/7/65—R. J. Allen 18
Vacuum Deposition—3,238,918, 3/8/66—R. P. Radke and W. E. Balin 933

VAPOR DEGREASING

Metal Treating (Vapor Degreasing)—3,230,175, 1/18/66—T. F. Martens 818
Vapor Degreaser—3,238,065, 3/1/66—L. Fullhart Jr. 933
Degreaser—3,242,933, 3/29/66—S. C. Huff 1053

VAPOR DEPOSITION

Vapor Deposition—3,218,203, 11/16/65—R. Ruehrwein 512
Vapor Deposition—3,219,482, 11/23/65—W. Jenkin 521
Vapor Deposition—3,230,109, 1/18/66—J. V. Domaleski 817
Vapor Deposition—3,233,578, 2/8/66—E. R. Capita 819
Vapor Deposition—3,244,554, 4/5/66—H. B. Prestridge 1053
Vapor Deposition—3,244,557, 4/5/66—C. Chiou 1053
Vapor Deposition—3,249,473, 5/3/66—N. Holonyak Jr. 1257
Vapor Deposition—3,252,823, 5/24/66—H. W. Jacobson 1383
Vapor Deposition—3,253,945, 5/31/66—T. K. Canley and J. I. Maher 1384
Vapor Deposition—3,253,946, 5/31/66—J. Kozikowski 1384

VAPOR PLATING

Vapor Plating—3,203,827, 8/31/65—F. Hill 18
Vapor Plating—3,206,326, 9/14/65—T. W. Haley and V. Norman ... 18
Vapor Plating—3,220,875, 11/30/65—P. Queneau 708

VIBRATORY FINISHING

Finishing—3,238,674, 3/8/66—R. W. Moore 933
Laboratory Finishing—3,213,568, 10/26/65—P. Setzler 511
Mechanical Finishing—3,248,826, 5/3/66—H. G. Van Fossen 1256
Vibratory Finishing—3,239,968, 3/15/66—R. W. Moore 934

Z

ZINC

Phosphatizing Zinc—3,240,633, 3/15/66—L. P. Gowman and J. L. Maurer 934
Process of Treating Deposits—3,245,779, 4/12/66—T. I. Moore and R. K. Carpenter 1157
Zincate Additive—3,216,835, 11/9/65—E. Saubestre 512

Advertising Index

This index is published entirely as a convenience. Every care for accuracy has been exercised. No assurance can be given, however, against inadvertent error.

A
Aldoa Company, The 1420
Allied Chemical Corp.
B & A Products 1413
Industrial Chemicals Div. ..Third Cover
Allied Research Products, Inc. 1483
Amchem Products Inc. 1411
American Buff Co. 1457
American Chemical & Refining Co., Inc. 1458

B
Baker Company, M. E. 1497
Belke Manufacturing Co. 1410

C
C & M Corporation 1497
Cadmium Corp. of America 1497
Chemical Corporation, The 1489
Continental Lacquer Corp. 1457
Conversion Chemical Corp. 1510
Coral Chemical Co. 1429

D
Diamond Sandblast Equipment 1497
Dow Chemical Co., The 1418A, 1418B
Duggan Masking Devices 1482

F
Federated Metals Division of Asarco 1426

G
General Tire & Rubber Co. Chemical/Plastics Division 1424

H
Hardwood Line Mfg. Co. 1414
Harshaw Chemical Co., The 1406, 1478, 1485, 1486, 1496
Hill Cross Co., Inc. 1481
Hubbard Hall Chemical Co. 1421

I
Illinois Water Treatment Co. 1484

L
Lea Manufacturing Co., The 1461
Lea Ronal, Inc. 1419
Lindale Equipment & Supply Corp. 1497

M
M&T Chemicals Inc. .....1403, 1409, 1422–1423, Fourth Cover
MacDermid, Inc. 1466A, 1466B
MART 1497
Meaker Company, The 1418
Michigan Buff Co. 1497
Minnesota Mining & Mfg. Co. Industrial Tape Div. 1427
Mitchell-Bate Co., The 1477

N
New Holland Machine Co. 1408
Northwest Chemical Co. 1415

O
Oakite Products Inc. 1430

P
Penfield Mfg. Co. 1472
Photovolt Corporation 1510
Plating Products, Inc. 1498
Professional Directory 1497

S
Schaffner Mfg. Co., Inc. 1480
Sel-Rex Corp. .....Second Cover
Service Filtration Corp. 1481
Sellers Manufacturing Co. 1425
Sethco Manufacturing Corp. 1404, 1491
Spraying Systems Co. 1482
Stainless Steel Co. 1497
Stutz Company 1475
Summit Scientific Corp. 1479

T
True Brite Chemicals Products Co. . 1498

U
Udylite Corporation ...1416–1417, 1482A
Unit Process Assemblies, Inc. ...1456, 1477
Unitron Instruments Co. 1473

Z
Zialite Corporation 1478

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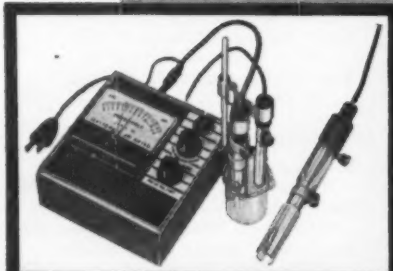

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